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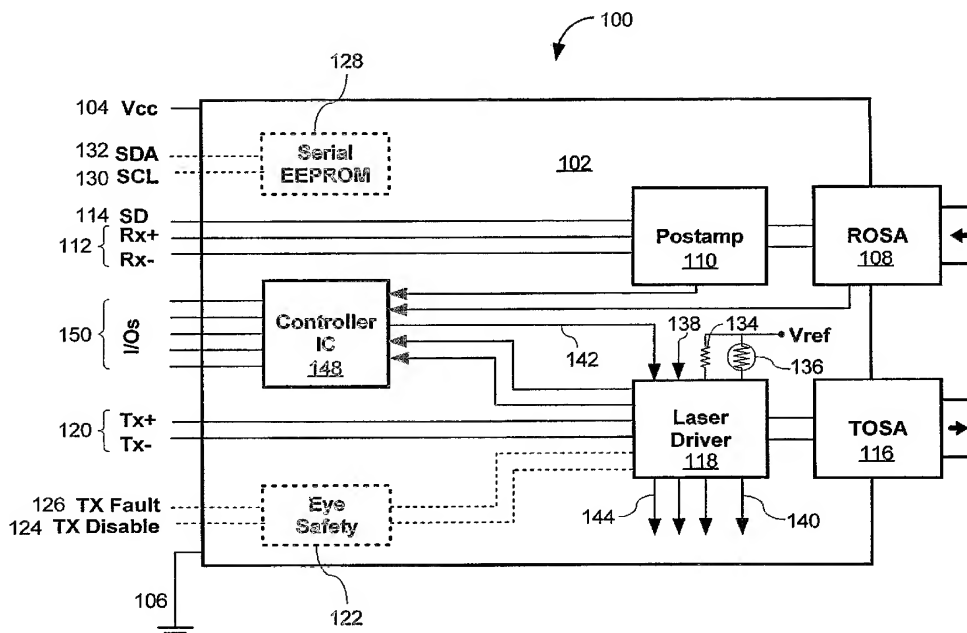
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(54) Title: OPTICAL TRANSCIVER MODULE WITH POWER INTEGRATED CIRCUIT



(57) Abstract: The optical transceiver module includes a housing and a plurality of components disposed at least partially within the housing. The components include an optical transmitter, an optical receiver, and a power controller integrated circuit (IC). The power controller (IC) is electrically coupled to at least one of the plurality of components. The power controller (IC) is configured to perform power supply functions for the optical transceiver module. Also, the power controller (IC) includes multiple voltage regulators providing power to the components at two or more voltages.



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OPTICAL TRANSCEIVER MODULE WITH POWER INTEGRATED CIRCUIT

FIELD OF THE INVENTION

5 The present invention relates generally to the field of fiber optic transceivers and particularly to an optical transceiver having an internal power controller integrated circuit (IC) for regulating and supplying power to the various components within the optical transceiver module.

DESCRIPTION OF RELATED ART

10 Fiber optic transceivers, otherwise known as optoelectronic transceivers, transmit and receive both light and electronics signals, i.e., they provide for the bi-directional communication of signals between an electrical interface and an optical interface.

 Figure 1 is a schematic representation of the circuitry and components found in various prior-art fiber optic transceivers 100. The fiber optic transceiver 100
15 includes a circuit board 102 that contains at a minimum a receiver circuit, a transmit circuit, a power connection 104, and a ground connection 106.

 The receiver circuit receives relatively small optical signals at an optical detector and amplifies and limits the signals to create a uniform amplitude digital
20 electronic output. The receiver circuit typically consists of a Receiver Optical Subassembly (ROSA) 108, which typically includes a fiber receptacle as well as a photodiode and pre-amplifier (preamp) circuit. The ROSA 108 is in turn connected to a post-amplifier (postamp) integrated circuit (IC) 110, which generates a fixed output swing digital signal which is connected to outside circuitry via RX+ and RX- pins
25 112. The postamp IC 110 also often provides a digital output signal known as Signal Detect (SD), or Loss of Signal (LOS), indicating the presence or absence of a suitably strong optical input. This Signal Detect (SD) output is provided via a SD output pin 114.

 The transmitter circuit, or laser driver circuit, accepts high speed digital data
30 and electrically drives a Light Emitting Diode (LED) or laser diode to create equivalent optical pulses. The transmit circuit typically consists of a Transmitter Optical Subassembly (TOSA) 116 and a laser driver IC 118. The TOSA 116 typically

includes a fiber receptacle as well as a laser diode or LED. The laser driver IC 118 typically includes an alternating current (AC) driver to provide AC current to the laser diode or LED. The laser driver IC 118 also typically includes a direct current (DC) driver to provide bias current to the laser diode or LED. The signal inputs for the AC driver are obtained from TX+ and TX- pins 120.

In addition, some optical transceiver standards require additional transceiver functionality. For example, the GigaBit Interface Converter (GBIC) standard requires eye safety and general fault detection functionality. This functionality is used to identify abnormal and potentially unsafe operating parameters and to report these to the user and/or perform laser shutdown, if appropriate. This functionality may be integrated into the laser driver IC 118 itself or into an optional eye safety IC 122. To enable this functionality, TX disable 124 and TX fault 126 pins are provided. The TX disable pin 124 allows the TOSA 116 to be shut off by a host device, while the TX fault pin 124 communicates a fault condition in the laser, or associated laser driver IC 118, to the host device. In addition to this basic description, the GBIC standard includes a series of timing diagrams describing how these controls function and interact with each other to implement reset operations and other actions. The GBIC standard also requires an Electrically Erasable Programmable Read Only Memory (EEPROM) 128 to store standardized serial identification (ID) information that can be read via a serial interface (defined as using the serial interface of the ATMEL AT24C01A family of EEPROM products) consisting of clock 130 and data 132 lines.

In use, various components, such as the laser driver IC 118, typically require individual setup and adjustment. Setup of these components generally occurs each time the optical transceiver is powered-up, as the individual components generally have volatile memories that lose setup data when powered-down. Adjustment, on the other hand, is typically required to account for variations in component characteristics, such as laser diode threshold current and slope efficiency either on a part to part basis or based on temperature. Parameters that are adjusted are: bias current and AC modulation. This setup and adjustment is generally performed on each optical transceiver by adjusting variable resistors or by connecting resistors 134, having factory selected resistance values, to the laser driver IC 118. Additionally, temperature compensation of the bias current and modulation is often required, which

is important to key laser characteristics, such as slope efficiency. Temperature compensation can be integrated into the laser driver IC 118 or accomplished through the use of external temperature sensitive elements, such as thermistors 136.

The above described optical transceiver has a number of drawbacks. For example, it is time consuming and costly to detect the variations of the various components, select the correct resistors 134 and thermistors 136 (or adjust the variable resistors), and/or install these on the circuit board 102 of the optical transceiver 100. In addition, such resistors and/or thermistors take up valuable space on the circuit board 102. Moreover, each time additional features are added to the optical transceiver, the complexity of the circuitry increases significantly. For example, in use, as many as twelve connections may be needed to the transmitter circuit, thereby significantly increasing circuitry complexity. Still further, such prior art systems are generally not scalable, i.e., they cannot easily be expanded to allow additional functionality.

More recently, analog signal lines have been introduced to setup and adjust these components. The analog signals lines may include analog inputs 138, such as bias current, modulation amplitude, and disable inputs, or analog outputs 140, such as actual bias, temperature, and output power. However, these analog signals lines do not address many of the drawbacks of the abovementioned prior art. For example, a high number of inputs and outputs are still required, which leads to complex circuitry that takes up a significant amount of space on the circuit board 102. These optical transceivers are still not scalable.

Dedicated digital connections, such as serial input 142 and output 144 connections, to these components have been introduced. An example of a digital output is a fault indicator, e.g., indicating that the transceiver module is running too hot. Optical transceivers employing these dedicated digital connections typically include a controller IC 148 located either within, or outside, the optical transceiver 100. Inputs and/or outputs 150 between the host and the controller IC 148 are typically also provided. However, optical transceivers employing dedicated digital connections do not fully address the abovementioned drawbacks. For example, the circuitry is still highly complex, especially for multiple inputs/outputs. This circuitry, as in other prior art optical transceivers, takes up valuable circuit board space.

In light of the above, an optical transceiver that addresses the abovementioned drawbacks would be highly desirable. In particular, such an optical transceiver should be simple to manufacture and operate; reduce complexity by providing a simple circuitry layout; use a minimal amount of circuit board space; and allow for scalability.

In addition, modern optical transceiver modules include a multitude of components, sometimes requiring two or more separate power sources and/or a different power supply voltages. For example, while many transceiver components require a voltage of 1.7v to 6v, an Avalanche Photo Diode (APD) typically requires anywhere from 40v to 75v. These, voltages supplied to the various components are typically supplied by discrete power sources, or power sources external to the optical transceiver module. Such power sources take up valuable space and add further expense to the overall optical transceiver system. Also, these power sources are typically fixed and not adjustable by the optical transceiver module itself. Furthermore, there are instances in which the use of a certain component in an optical transceiver would be preferred, but due to the requirement of a different power supply not available in the transceiver module, another component is used in its place.

In light of the above, an optical transceiver that includes a power controller having multiple power sources within the optical transceiver module would be highly desirable. Such power sources should be simple to manufacture and operate, should reduce complexity by providing a centralized source of power, and should require a minimal amount of circuit board space. Furthermore, it would be desirable for one or more of the power sources of the power controller to be adjustable, so as provide power to a variety of different components that might be included in a transceiver module. More generally, having one or more adjustable power sources in a power controller would allow for future modifications and scalability of the optical transceiver modules in which the power controller is used.

SUMMARY OF THE INVENTION

According to the invention there is provided an optical transceiver module. The optical transceiver module includes an optical transmitter, such as a laser in a TOSA, and an optical receiver, such as a PIN detector in a ROSA. The optical transceiver module also includes an internal serial bus and a plurality of addressable

components electrically coupled to the internal serial bus. Each of the addressable components includes a serial interface for communicating with the internal serial bus, and a memory. Each addressable component also includes a unique address, or chip select logic coupled to a controller via a chip select line. This allows data to be
5 addressed to specific addressable components. The addressable components may also include an analog to digital converter and/or a digital to analog converter. The plurality of addressable components may include components selected from a laser driver, a laser bias controller, a power supply circuit or controller, a pre-amplifier, a post-amplifier, a laser wavelength controller, a main controller, a thermoelectric
10 cooler (TEC), an analog-to-digital converter, a digital-to analog converter and/or an APD bias controller, or any combination of these components.

Consequently, the above described transceiver module includes a single, shared internal serial bus that connects to numerous components in the transceiver module. This allows a plurality of functions to be performed via a single electrical
15 connection to each component. Also, overall system complexity is reduced by eliminating the need for multiple analog or digital lines to each component. This conserves valuable board area for other components or circuitry and may even allow for a more compact transceiver module. In addition, the internal serial bus allows for scalability. For example, new integrated circuits (ICs) may be coupled to the internal
20 serial bus, thereby sharing input and output ports on the main controller. These input and output ports are generally used for sending setup commands to the ICs or receiving monitoring information from the ICs. In addition, new ICs having additional functionality or features may be swapped with existing ICs without requiring any additional input and output ports, i.e., adding functionality with little circuit redesign.

25 Moreover, the above described transceiver module provides more complete and accurate control and monitoring of the transceiver module's parameters.

According to the invention there is provided an optical transceiver module. The optical transceiver module includes housing and a plurality of components disposed at least partially within the housing. The components include an optical
30 transmitter, an optical receiver, and a power controller integrated circuit (IC). The power controller IC is electrically coupled to at least one of the plurality of components. The power controller IC is configured to perform power supply

functions for the optical transceiver module. Also, the power controller IC includes multiple voltage regulators providing power to the components at two or more voltages.

In a preferred embodiment, at least one of the multiple voltage regulators is a
5 low drop-out voltage regulator configured to receive an unregulated input voltage and configured to supply a regulated output voltage to at least one of the components. Also in a preferred embodiment, at least one of the multiple voltage regulators is a boost or buck regulator electrically coupled to at least one of the components. The power controller IC may further include a serial bus within the power controller IC.
10 The multiple voltage regulators may then be electrically coupled to the serial bus. The power controller IC may further include a serial interface electrically coupled to the serial bus.

In a preferred embodiment, the components further include a main controller electrically coupled to the serial interface, a laser driver IC electrically coupled to the
15 optical transmitter, and a post-amplifier IC electrically coupled to the optical receiver. In use, the main controller can control at least one of the multiple voltage regulators. Each of the voltage regulators are preferably individually addressable. At least one of the voltage regulators also preferably includes an Avalanche Photo Diode (APD) voltage supply. Also, at least one of the voltage regulators is preferably adjustable. In
20 a preferred embodiment, the power controller IC further includes an analog to digital converter, a temperature sensor, a digital to analog converter, a logic module, an inrush current limiter, and a processor management module.

In this way, a single power controller IC is used to supply power to the various components within the optical transceiver. This power controller IC is simple to
25 operate and clearly reduces circuitry complexity by providing a centralized source of power. Furthermore, a single power controller IC requires significantly less circuit board space than prior power sources. In addition, such power sources are adjustable, i.e., the main controller can set the voltages and/or shutdown the regulators, if necessary. This adjustability may be used to compensate for component degradation
30 over time. In other words, as a component degrades over time its voltage requirements may increase. Moreover, such adjustability provides for the power requirements of future optical transceivers without requiring a complete redesign of the power supply.

Such adjustability also makes such an optical transceiver more scalable. Finally, the power controller IC provides for more precise temperature control and compensation.

BRIEF DESCRIPTION OF THE DRAWINGS

For a better understanding of the nature and objects of the invention, reference
5 should be made to the following detailed description, taken in conjunction with the accompanying drawings, in which:

Figure 1 is a schematic representation of the circuitry and components of various prior-art fiber optic transceivers;

Figure 2A is a schematic representation of the circuitry and components of an
10 optical transceiver module that uses a component address serial protocol, according to an embodiment of the invention;

Figure 2B is a schematic representation of the circuitry and components of an optical transceiver module that uses a chip select serial protocol, according to another embodiment of the invention;

15 Figure 2C is a schematic representation of the circuitry and components of an optical transceiver module, according to another embodiment of the invention;

Figure 3 is a schematic representation of a system utilizing fiber optic transceiver modules similar to that shown in Figures 2A and 2B;

Figure 4A is a schematic representation of an exemplary addressable
20 component of the optical transceiver module shown in Figure 2A;

Figure 5 is a schematic representation of the power controller integrated circuit (IC) shown in Figures 2A and 2B.

Like reference numerals refer to corresponding parts throughout the several views of the drawings. For ease of reference, the first number of any reference
25 numeral generally indicates the figure number in which the reference numeral can be found. For example, 132 can be found in Figure 1, and 304 can be found in Figure 3.

DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS

The present invention utilizes a shared internal serial bus to communicate with multiple addressable components in an optical transceiver module. As will be shown,
30 the shared serial bus simplifies overall transceiver setup, control, monitoring, and safety functions, while reducing system complexity, freeing-up valuable board space, and allowing for scalability. In a preferred embodiment, the serial bus monitors: laser

bias current from the laser bias controller; laser output power; received average power; received modulated power; APD bias voltage; temperature; current in a thermoelectric cooler (TEC) controller; temperature in the TEC controller; wavelength; error rates; signal integrity; or the like.

5 Figure 2A is a schematic representation of the circuitry and components of an optical transceiver module that uses a component address serial protocol, according to an embodiment of the invention. The transceiver module 200 preferably includes at least one circuit board 202 having multiple addressable components disposed thereon. The transceiver module 200 is preferably at least partially contained within a
10 transceiver housing 204. The transceiver module 200 includes an optical interface 206 for receiving and transmitting optical signals, and an electrical interface 208 for receiving and transmitting electrical signals. The transceiver module 200 contains a ROSA 210 electrically coupled to a post amplifier IC 212, and a TOSA 214 electrically coupled to a laser driver IC 216.

15 The ROSA 210 receives relatively small optical signals at an optical receiver or detector, such as a photodiode 213. These signals are converted to electrical signals and amplified by the post-amplifier IC 212 to create a uniform amplitude digital electronic output, which is transmitted to external circuitry via RX+ and RX- pins 218. The post-amplifier IC 212 also preferably provides a digital output signal known
20 as Signal Detect (SD), or Loss of Signal (LOS), at LOS pin 220, indicating the presence or absence of a suitably strong optical input.

 In a preferred embodiment, the small optical signals received at the ROSA are first amplified by a pre-amplifier IC 215, generally located within the ROSA package, before being sent to the post-amplifier IC 212. In an alternative embodiment, the pre-
25 amplifier IC 215 is coupled directly to a shared serial bus 222.

 The post-amplifier IC 212 is also preferably an addressable component electrically coupled to a shared serial bus 222 via a serial connection. The shared serial bus 222 is preferably located on the circuit board 202, at least partially internal to the transceiver housing 204. A number of digital signals and/or data may be
30 communicated between the post-amplifier IC 212 and the main controller 226, or other devices within the transceiver, via the shared serial bus 222. Such digital signals and/or data may include: output amplitude setting data, slew rate data, LOS thresholds

and status data, equalization data, received signal power, loss of signal data, or a subset of these.

The laser driver IC 216 accepts high speed digital data from external circuitry to electrically drive the TOSA 214 to create equivalent optical pulses. The TOSA 214
5 preferably contains an optical transmitter, such as a LED or laser diode 211. The laser driver IC 216 preferably includes an AC driver to provide AC current to the laser diode or LED. The signal inputs for the laser driver IC 216 are obtained from TX+ and TX- pins 224.

The laser driver IC 216 is also preferably an addressable component
10 electrically coupled to the shared serial bus 222 via a serial connection. A number of digital signals and/or data may be communicated between the laser driver IC 216 and the main controller 226, or other devices within the transceiver module 200, via the shared serial bus 222. Such digital signals and/or data may include: modulation amplitude data, slew rate data, equalization data, other control parameters or
15 monitoring data, or any subset of these.

The transceiver module 200 also preferably includes a number of other addressable components, such as a main controller IC 226, a laser bias controller IC 228, a power controller IC 230, and an ill memory and status IC 234, or a subset of these. Each of the aforementioned addressable components is electrically coupled to
20 the shared internal serial bus 222 via a separate serial connection.

The main controller IC 226 implements most setup, control, and monitoring functions of the transceiver module 200, such as temperature compensation, diagnostic feedback, variation adjustments and calibration, or the like. The main controller IC 226 also acts as the serial bus master for the shared serial bus 222.
25 Although not shown, the main controller IC 226 preferably includes a non-volatile memory. Further description of a similar main controller IC can be found in co-pending U.S. Patent Application No. 09/777,917, which is incorporated herein by reference.

The laser bias controller IC 228 is used to control key parameters of the laser
30 driver IC 216 and the TOSA 214, such as safety and general fault detection functionality.

This functionality is used to identify abnormal and potentially unsafe operating parameters and to report these to the user and/or perform laser shutdown, if appropriate. To enable this functionality, TX disable 242 and TX fault 244 pins are provided. The TX disable pin 242 allows the TO SA 214 to be shut off by a host
5 device. The TX fault pin 244 communicates a fault condition in the laser or LED, or associated laser driver IC 216, to a host device (not shown).

In one embodiment, the laser bias controller IC 228 is also preferably electrically coupled directly to the TOSA 214. This direct electrical connection to the TOSA 214 is used to directly control the laser bias current and the AC modulation
10 level to the TOSA 214, thereby operating the laser driver in a constant bias mode operation. A direct electrical connection to the TOSA 214 is also preferably used to receive a laser power feedback from the TOSA 214.

In another embodiment, the outputs of the laser bias controller IC 228 control the level of average output power of the laser driver IC 216 in addition to the AC
15 modulation level, thereby operating the laser driver in a constant power mode operation.

The laser bias controller IC 228 is also electrically coupled to the shared serial bus 222 via a serial connection. A number of digital signals and/or data may be communicated between the laser bias controller IC 228 and the serial bus 222. Such
20 digital signals and/or data include: bias settings and status, power settings and status, error thresholds and status, temperature compensation settings, other control settings, other status signals, or a subset thereof.

The power controller IC 230 provides and regulates power to the transceiver module 200. A power supply is connected to the module 200 at power supply input
25 pins 246. The power controller IC 230 is also electrically coupled to all components that require a power supply. The power controller IC 230 is also electrically coupled to the serial bus 222 via a serial connection. A number of digital signals and/or data may be communicated between the power controller IC 230 and the main controller 226, or other devices within the transceiver module 200, via the serial bus 222. Such
30 digital signals and/or data include: voltage commands, voltage and current status, temperature, power down or sleep mode, control signals, step-up signals, step-down signals, surge control functions, or the like. The power controller IC 230 preferably

includes two or more voltage regulators, with each voltage regulator providing either a fixed or programmable voltage that can be supplied to one or more of the components of the transceiver module 200. The power controller IC 230 is coupled to each of the other components of the transceiver module 200 that require regulated power. Since each of the components or IC's in the transceiver 200 potentially requires a different regulated supply voltage, the power controller IC 230 may be implemented using multiple integrated circuits, including two or more voltage regulator IC's and a logic circuit IC.

A host serial interface controller 236, coupled directly to the main controller 226, communicates with a host device (not shown). The host serial interface controller 236 couples to a host serial bus (not shown) via clock 248 and data 250 lines. The host serial interface controller 236 is used for all setup and querying of the main controller IC 226. In a preferred embodiment, the host serial interface controller 236 operates in accordance with a two wire serial interface standard that is used in the GBIC and SFP (Small Form Factor Pluggable) standards. A host serial bus (not shown), coupled to the host serial interface controller 236, is preferably an I2C (Inter-IC) or MDIO bus. An I2C or I2C bus is a bi-directional two-wire serial bus that provides a communication link between integrated circuits. An MDIO bus is a Management Data Input/Output bus, as described by the IEEE 802.3 specification. Alternatively, another bi-directional serial interface could be used.

In the embodiment shown in Figure 2A, the internal serial bus 222 utilizes a component address serial protocol that addresses each addressable component using the component's unique component address 418 (Figure 4A), as described below. Examples of a suitable component address serial protocol include I2C (or I2C) and MDIO.

In some embodiments the transceiver module 200 also includes a laser wavelength controller IC 252 coupled to the TOSA 214 and to the shared serial bus 222. The laser wavelength controller IC 252 preferably controls the temperature of the laser diode in the TOSA 214 so as to control wavelength of the light generated by the laser diode. A suitable wavelength controller IC 252 is a thermoelectric cooler (TEC). The laser wavelength controller IC 252 may also control the wavelength by any other suitable means, such as voltage, current bias, or the like. Precise control of the laser

wavelength is important in wavelength division multiplexing applications, in which light from multiple laser diodes at multiple respective wavelengths is transmitted over a single optical fiber. The light at each wavelength is used to transmit a distinct signal or data stream. The laser wavelength controller IC 252 provides a laser temperature drive 256 to the TOSA 214, and receives laser temperature or wavelength feedback 258 from the TOSA 214.

The laser wavelength controller IC 252 is also preferably an addressable component electrically coupled to the shared serial bus 222 via a serial connection. A number of digital signals and/or data may be communicated between the laser wavelength controller IC 252 and the main controller 226, or other devices within the transceiver module 200, via the shared serial bus 222. Such digital signals and/or data include: temperature and/or wavelength commands and status, temperature control status, temperature control current, and the like, or any subset of these signals and data.

In embodiments where the ROSA 210 includes an avalanche photodiode, the transceiver module 200 preferably also includes an avalanche photodiode (APD) bias control IC 254 coupled to the ROSA 210 and to the shared serial bus 222. The APD bias control IC 254 transmits a bias signal to the ROSA 210 for controlling the operation of the avalanche photodiode in the ROSA 210.

The APD bias control IC 254 is also electrically coupled to the shared serial bus 222 via a serial connection. A number of digital signals and/or data may be communicated between the APD bias control IC 254 and the main controller 226, or other devices within the transceiver module 200, via the shared serial bus 222. Such digital signals and/or data include: bias voltage (command and status), bias current, temperature compensation control and/or monitoring signals, or any subset of these signals.

Figure 2B is a schematic representation of the circuitry and components of an optical transceiver module that uses a chip select serial protocol. This embodiment is identical in all respects to the embodiment described in relation to Figure 2A, except that the individual addressable components are addressed by dedicated hardware in the form of chip selects, shown as CS I-CS7. Dedicated chip select lines or wires CS I-CS7 couple the main controller 226 (master) to each addressable component (slave).

Each chip select is a signal that when true permits input and output of the addressable component's memory, and when false prohibits such input and output. (See the discussion below of component memory 404.) Therefore, in use, each time input or output from an addressable component is required, the main controller 226 (Figure 2) sends a chip select signal only to that particular addressable component, thereby allowing input or output to that addressable component. It should be appreciated that although only seven chip select lines are shown, either more or less chip select lines may be used.

This embodiment is simpler to manufacture and is less expensive than the embodiment described in Figure 2A. However, a dedicated chip select line running to each addressable component takes up valuable board area. A suitable chip select serial protocol is Serial Peripheral Interface (SPI) that utilizes a data-in pin, a data-out pin, a clock pin, and a chip select pin on each component.

Figure 2C is a schematic representation of the circuitry and components of an optical transceiver module, according to another embodiment of the invention. This embodiment illustrates that the components within the optical transceiver module may be combined. For example, the optical transceiver module may include a single: laser driver and laser bias controller 262; power controller and APD Bias Controller 264; and pre-amplifier and post-amplifier 266. It should, however, be appreciated that these combined components are merely exemplary and any other combination of components may be used.

Figure 3 is a schematic representation of a system 300 utilizing fiber optic transceiver modules (also known as optoelectronic transceivers) similar to that shown in Figure 2. First host 302 is electrically coupled to a first optical transceiver module 304 via electrical links 306. These electrical links 306 preferably connect to the input/output pins of the first optical transceiver module 304. These input/output pins preferably include the connections or pins shown in Figure 2 as Tx+ and Tx- 224, Tx disable 242, Tx fault 244, the power supply 246, data 250, clock 248, LOS 220, and Rx+ and RX- 218 pins. Likewise, a second host 308 is electrically coupled to a second optical transceiver module 310 via electrical links 312. Also, the first and second optical transceivers 304 and 310 are optically coupled to one another via optical fibers 314, i.e., TOSA to ROSA.

Figure 4A is a schematic representation of an exemplary addressable component 400 of the optical transceiver module 200 shown in Figure 2A. As described above, the addressable component 400 is preferably a single integrated circuit (IC). The exemplary addressable component 400 may be any addressable component in the transceiver module 200 that is coupled to the shared serial bus 222 (Figure 2A or 2B), such as the laser driver IC 216 (Figure 2A), post-amplifier IC 212 (Figure 2A), or the like. The addressable component 400 includes a serial interface 402 coupled to the internal serial bus 222 (Figure 2) via data 412 and clock 414 lines. The serial interface 402 preferably communicates with other devices coupled to the serial bus 222 (Figure 2) using any suitable signaling protocol, such as a component address serial protocol like I2C or MDIO, as described above in relation to Figure 2A, or a chip select serial protocol, like SPI, as described above in relation to Figure 2B.

Each addressable component 400 also preferably includes a memory 404 for storing data, such as monitored variables, commands and/or control parameters received from other components or from a host device, or the like. The memory 404 may include a memory array or one or more registers, or both a memory array and registers, and may include volatile and/or non-volatile memory components or registers. The memory may also include a FIFO, cache, or the like. In some addressable components 400, the memory 404 may have very few memory elements (e.g., command and/or feedback registers) or locations that are used by the component, while other components may have a larger number of memory elements or locations.

The addressable component 400 also preferably includes a digital to analog converter (DAC) 410 for converting digital data received at the serial interface 402 into analog signals that can be used by the addressable component 400. If none of the data or control parameters received by a particular addressable component 400 require conversion into an analog signal, a DAC 410 need not be included in the addressable component. For instance, on/off control parameters received by an addressable component can usually be converted into control signals without the use of a DAC 410. Thus, some of the addressable components 400 in a transceiver module may include a DAC 410 while one or more of the other components do not include a DAC 410.

In addition, the addressable component 400 preferably includes an analog to digital converter (ADC) 408 for converting analog signals to digital signals that can be transmitted to the internal serial bus 222 (Figure 2) via the data line 412. The analog signals coupled to the ADC 408 are typically voltage or current signals whose magnitude or value is being monitored. If there are no analog signals in the addressable component whose magnitude or value is being monitored, an ADC 408 need not be included in the addressable component. Thus, some of the addressable components 400 in a transceiver module may include an ADC 408 while one or more of the other components do not include an ADC 408.

Other circuitry 406 in the addressable component 400 performs the setup, control, monitoring, and/or safety functions of the addressable component, as described above in relation to Figure 2.

If the addressable component 400 utilizes a component address serial protocol like I2C or MDIO, as described in relation to Figure 2A, the addressable component 400 preferably includes a unique address 418, which enables data/signals to be sent to and from a specific addressable component 400 via the shared, internal serial bus 222 (figure 2) and data line 412.

Figure 4B is a schematic representation of an exemplary addressable component 422 of the optical transceiver module 200 shown in Figure 2B. This embodiment is identical in all respects to the embodiment described in relation to Figure 4A, except that the addressable component 422 does not include an address 418 and rather includes chip select logic 420 coupled to a chip select line 416. This embodiment utilizes a chip select serial protocol, such as SPI, as described in relation to Figure 2B. In use, each time input or output from an addressable component is required, the main controller 226 (Figure 2) sends a chip select signal only to that particular addressable component, thereby allowing input or output to that addressable component.

Consequently, the above described transceiver module 200 (Figure 2) includes a shared internal serial bus 222 (Figure 2) that connects to a plurality of addressable components 400 (Figure 4A) or 422 (Figure 4B) in the transceiver module 200 (Figure 2). This allows a plurality of functions to be performed via a single digital electrical connection that is coupled to each addressable component. Also, overall

system complexity is reduced by eliminating or reducing the need for multiple analog or digital lines to each component. This conserves valuable board area for other components or circuitry and may even allow for a smaller transceiver package or housing 204 (Figure 2A). In addition, the shared internal serial bus allows for
5 scalability, i.e., allowing additional functionality to be added to a transceiver with very little circuitry redesign.

One use of such a single, shared internal serial bus is to address problems associated with jitter, such as deterministic jitter and in particular pattern dependent jitter. Typically, jitter refers to bit transitions offset in time from the norm, i.e.
10 occurring either before or after a uniformed clocked period. In other words, Jitter is a bit arriving either ahead or behind a standard clock cycle.

To address problems associated with jitter, the main controller 226 (Figure 2A-2C) recognizes preceding bits or patterns and adjusts a delay to ensure that the bit transitions are not offset in time and occur at a uniformed standard clock cycle.

15 Any attempt to address jitter in prior art devices would necessitate a separate control line for each delay or source of jitter that is to be adjusted. This solution may not be practical if a large number of separate control lines are required to address a corresponding number of delays or sources of jitter. However, by using a single, shared internal serial bus, the present invention allows for the monitoring and
20 correction of jitter, as only one line or communication bus is needed.

Another advantage is in an embodiment that incorporates the laser driver IC 216 (Figure 2A) into the TOSA 214 (Figure 2A). This embodiment would be impractical in the prior art, as too many control and monitoring lines would be needed by the combined component. Again, however, the present invention allows for such a
25 combined component, as only a single, shared serial bus need be connected to the combined component for conveying control signals to the components and for receiving status monitoring information from the component.

It should be appreciated by those skilled in the art that each of addressable components described herein may comprise a single IC, multiple IC's, analog
30 circuitry, a combination IC's and analog circuitry, or the like. Also, it should be appreciated to those skilled in the art that despite the fact that the preferred

embodiment described above utilizes a single, shared serial bus, more than one internal serial bus may be provided in other embodiments of the present invention.

Figure 5 is a schematic representation of the power controller integrated circuit (IC) 230 shown in Figures 2A and 2B. In a preferred embodiment, the power
5 controller IC 230 is a single integrated circuit that both supplies and regulates power to the remainder of the transceiver module 200 (Figure 2). Alternatively, the power controller IC 230 may be split between two or more integrated circuits.

The power controller IC 230 preferably includes multiple components integrated within the power controller IC 230, such as voltage regulators, converters,
10 and the like. The power controller IC 230 is preferably coupled to an external power supply at power supply input (Vcc and Ground) 246. The power controller IC 230 also preferably includes its own internal serial bus 512, such as a Serial Peripheral Interface (SPI) bus, which is used to communicate synchronously over short distances at up to 4Mbit/s. This serial bus 512 is internal to the power controller IC 230, and
15 facilitates communication between the various components within the power controller IC 230, where each of the various components within the power controller IC 230 has a unique component address.

The power controller IC 230 preferably includes two or more voltage regulators 504-510 that provide regulated voltage to the various components within
20 the optical transceiver module. Each voltage regulator provides either a fixed or adjustable voltage that can be supplied to one or more of the components within the optical transceiver module. The voltage regulators 504-510 preferably include multiple low drop-out (LDO) voltage regulators 504 and 506. These LDO regulators 504 and 506 typically provide a regulated output voltage (V_{out}) that is only a small
25 drop in voltage from an unregulated input voltage (V_{in}). For example, an input voltage (V_{in}) of 1.7v to 6.0v is regulated to a 1.5v to 5.5v output voltage (V_{out}), typically at a preferred current of 150ma.

The voltage regulators 504-510 also preferably include at least one boost or buck regulator 508. This boost or buck regulator 508 either steps-ups or steps-down
30 the input voltage (V_{in}) to an output voltage (V_{out}). For example, an input voltage of 1.7v to 6.0v can be stepped-up or stepped-down to a 1.8v to 12.0v output voltage (V_{out}). Yet another one or more voltage regulators 504-510 is preferably an Avalanche

Photo Diode (APD) voltage supply 510. As an APD requires a large voltage to operate, the APD voltage supply 510 preferably supplies a 40v to 75v output voltage (Vout) (from a 1.7v to 6.0v input voltage, Vin), typically at a preferred current of 2ma.

5 The power controller IC 230 also preferably includes a serial interface 522 for coupling to and communicating with the optical transceiver module's internal serial bus 222 (Figures 2A-2B). In a preferred embodiment, the serial interface 522 operates in accordance with a two wire serial interface standard that is used in the GBIC and SFP (Small Form Factor Pluggable) standards for optical transceivers. For example,
10 the serial interface 522 may operate in accordance with the I2C (or I²C) or MDIO serial communication standard. Accordingly, communication can occur between any internal component within the power controller IC 230 and any other component that is coupled to the internal serial bus 222 (Figures 2A and 2B). Accordingly, a number of digital signals and/or data may be communicated between the power controller IC
15 230 and the main controller 226 (Figures 2A and 2B) - via the serial bus 512, the serial interface 522 and the internal serial bus 222 (Figures 2A and 2B). Furthermore, digital signals and/or data may be communicated between the power controller IC 230 and an external host - via the serial bus 512, the serial interface 522, the internal serial bus 222 (Figures 2A and 2B), and the serial interface 236 (Figures 2A and 2B). Such
20 digital signals and/or data may include: voltage commands, voltage and current status, temperature, power down or sleep mode commands or status information, control signals, step-up signals, step-down signals, surge control functions, or the like.

 The voltage regulators 504-510 are also preferably adjustable, i. e., the voltage regulators 504-510 are voltage programmable voltage regulators. In a preferred
25 embodiment, the voltage regulators 504-510 are separately addressable and coupled to the serial bus 512. This allows the main controller 226 (Figures 2A and 2B), that is coupled to the transceiver module's internal serial bus 222 (Figures 2A-2B), to program the voltage regulators 504-510 by specifying a desired voltage (V set) (i.e., by sending a voltage level setting command) during power-up. Also, the main
30 controller 226 (Figures 2A and 2B) may shutdown the voltage regulators 504-510, if necessary, such as if a fault condition is detected. Furthermore, level setting

commands are either sent continuously to each component at a predetermined rate, or only once during power up.

In addition, the power controller IC 230 also preferably includes a processor management module 528. The processor management module 528 is otherwise known as a power supply supervisory chip or watchdog. The processor management module 528 is preferably configured to monitor the regulated supply voltage and microprocessor activity, provide reset signals, retain the contents of any volatile memory by providing a low-current DC voltage to volatile memory when regular power is off, and determine when ordinary power has resumed.

The power controller IC 230 also preferably includes an inrush current limiter 502 coupled to the serial bus 512. High inrush current can be produced when the optical transceiver module is turned on. This high inrush current can cause problems in host equipment and exceed module specification limits. Accordingly, the inrush current limiter or surge limiter 502 reduces or limits inrush current by presenting a relatively high resistance at turn on, and gradually reduces its resistance to a small value to allow full supply voltage into the module.

The power controller IC 230 may also include other internal components, such as one or more analog to digital converters 518 (e.g., for monitoring one or more voltages or other signals within the optical transceiver module), one or more digital to analog converters 520 (each of which generates an output voltage or current in accordance with the digital value presented to the converter 520), a configurable logic module 524, one or more multiplexers, or the like. As the power controller IC 230 may generate considerable heat, a temperature sensor 514 may also be coupled to the analog to digital converter 518 to monitor the power controller IC's temperature.

In addition, the current limit Vout 530; LDO #1 voltage 532, LDO #2 voltage; boost/buck voltage 536; APD voltage 538; and APD current 540 are status and/or diagnostic monitor signals. These signals are preferably an analog voltage proportional to the respective outputs, which are digitized by the analog to digital converter 518. Alternatively, these signals are digital derived from a local analog to digital converter (or other means) within each component. These signals are used to monitor the performance and setting of the regulator, and may be used for feedback in closed loop control systems. Also, currents used or supplied by the various

components can be from a few milliamps delivered by the APD supply, up to an amp for the inrush limiter, or nominal 50ma to 150ma for the other regulators.

The foregoing descriptions of specific embodiments of the present invention are presented for purposes of illustration and description. They are not intended to be
5 exhaustive or to limit the invention to the precise forms disclosed. Obviously many modifications and variations are possible in view of the above teachings. For example, other embodiments may include fewer or more components, different combinations of components, different serial protocols, or the like. In another example, two or more of the components shown in Figure 5 may be combined into a single integrated circuit
10 having a single interface to the serial bus 512. Such combinations may be advantageous for reasons of cost, shared functionality, packaging requirements, power utilization, or the like. The embodiments were chosen and described above in order to best explain the principles of the invention and its practical applications, to thereby enable others skilled in the art to best utilize the invention and various embodiments
15 with various medications as are suited to the particular use contemplated. Furthermore, the order of steps in the method are not necessarily intended to occur in the sequence laid out. It is intended that the scope of the invention be defined by the following claims and their equivalents, In addition any reference cited above are incorporated herein by reference.

TABLE 1
MEMORY MAP FOR TRANSCEIVER CONTROLLER

Memory Location (Array 0)	Name of Location	Function
00h – 5Fh	IEEE Data	This memory block is used to store required GBIC data
60h	Temperature MSB	This byte contains the MSB of the 15-bit 2's complement temperature output from the temperature sensor.
61h	Temperature LSB	This byte contains the LSB of the 15-bit 2's complement temperature output from the temperature sensor. (LSB is 0b).
62h – 63h	V _{cc} Value	These bytes contain the MSB (62h) and the LSB (63h) of the measured V _{cc} (15-bit number, with a 0b LSbit)
64h – 65h	B _{in} Value	These bytes contain the MSB (64h) and the LSB (65h) of the measured B _{in} (15-bit number, with a 0b LSbit)
66h – 67h	P _{in} Value	These bytes contain the MSB (66h) and the LSB (67h) of the measured P _{in} (15-bit number, with a 0b LSbit)
68h – 69h	R _{in} Value	These bytes contain the MSB (68h) and the LSB (69h) of the measured R _{in} (15-bit number, with a 0b LSbit)
6Ah – 6Dh	Reserved	Reserved
6Eh	IO States	This byte shows the logical value of the I/O pins.
6Fh	A/D Updated	Allows the user to verify if an update from the A/D has occurred to the 5 values: temperature, V _{cc} , B _{in} , P _{in} and R _{in} . The user writes the byte to 00h. Once a conversion is complete for a give value, its bit will change to '1'.
70h – 73h	Alarm Flags	These bits reflect the state of the alarms as a conversion updates. High alarm bits are '1' if converted value is greater than

		corresponding high limit. Low alarm bits are '1' if converted value is less than corresponding low limit. Otherwise, bits are 0b.
74h – 77h	Warning Flags	These bits reflect the state of the warnings as a conversion updates. High warning bits are '1' if converted value is greater than corresponding high limit. Low warning bits are '1' if converted value is less than corresponding low limit. Otherwise, bits are 0b.
78h – 7Ah	Reserved	Reserved
7Bh – 7Eh	Password Entry Bytes PWE Byte 3 (7Bh) MSByte PWE Byte 2 (7Ch) PWE Byte 1 (7Dh) PWE Byte 0 (7Eh) LSByte	The four bytes are used for password entry. The entered password will determine the user's read/write privileges.
7Fh	Array Select	Writing to this byte determines which of the upper pages of memory is selected for reading and writing. 0xh (Array x Selected) Where x = 1, 2, 3, 4 or 5
80h – F7h		Customer EEPROM
87h	DA % Adj	Scale output of D/A converters by specified percentage

Memory Location (Array 1)	Name of Location	Function of Location
00h – FFh		Data EEPROM

Memory Location (Array 2)	Name of Location	Function of Location
00h – Ffh		Data EEPROM

Memory Location (Array 3)	Name of Location	Function of Location
80h – 81h 88h – 89h 90h – 91h 98h – 99h A0h – A1h	Temperature High Alarm V _{cc} High Alarm B _{in} High Alarm P _{in} High Alarm R _{in} High Alarm	The value written to this location serves as the high alarm limit. Data format is the same as the corresponding value (temperature, V _{cc} , B _{in} , P _{in} , R _{in}).

82h – 83h 8Ah – 8Bh 92h – 93h 9Ah – 9Bh A2h – A3h	Temperature Low Alarm V _{cc} Low Alarm B _{in} Low Alarm P _{in} Low Alarm R _{in} Low Alarm	The value written to this location serves as the low alarm limit. Data format is the same as the corresponding value (temperature, V _{cc} , B _{in} , P _{in} , R _{in}).
84h – 85h 8Ch – 8Dh 94h – 95h 9Ch – 9Dh A4h – A5h	Temp High Warning V _{cc} High Warning B _{in} High Warning P _{in} High Warning R _{in} High Warning	The value written to this location serves as the high warning limit. Data format is the same as the corresponding value (temperature, V _{cc} , B _{in} , P _{in} , R _{in}).
86h – 87h 8Eh – 8Fh 96h – 97h 9Eh – 9Fh A6h – A7h	Temperature Low Warning V _{cc} Low Warning B _{in} Low Warning P _{in} Low Warning R _{in} Low Warning	The value written to this location serves as the low warning limit. Data format is the same as the corresponding value (temperature, V _{cc} , B _{in} , P _{in} , R _{in}).
A8h – AFh , C5h B0h – B7h , C6h B8h – BFh , C7h	D _{out} control 0-8 F _{out} control 0-8 L _{out} control 0-8	Individual bit locations are defined in Table 4.
C0h	Reserved	Reserved
C1h	Prescale	Selects MCLK divisor for X-delay CLKS.
C2h C3h C4h	D _{out} Delay F _{out} Delay L _{out} Delay	Selects number of prescale clocks
C8h – C9h CAh – CBh CCh – CDh CEh – CFh	V _{cc} – A/D Scale B _{in} – A/D Scale P _{in} – A/D Scale R _{in} – A/D Scale	16 bits of gain adjustment for corresponding A/D conversion values.
D0h	Chip Address	Selects chip address when external pin ASEL is low.
D1h	Margin #2	Finisar Selective Percentage (FSP) for D/A #2
D2h	Margin #1	Finisar Selective Percentage (FSP) for D/A #1
D3h – D6h	PW1 Byte 3 (D3h) MSB PW1 Byte 2 (D4h) PW1 Byte 1 (D5h) PW1 Byte 0 (D6h) LSB	The four bytes are used for password 1 entry. The entered password will determine the Finisar customer's read/write privileges.
D7h	D/A Control	This byte determines if the D/A outputs source or sink current, and it allows for the outputs to be scaled.
D8h – DFh	B _{in} Fast Trip	These bytes define the fast trip comparison over temperature.
E0h – E3h	P _{in} Fast Trip	These bytes define the fast trip comparison over temperature.
E4h – E7h	R _{in} Fast Trip	These bytes define the fast trip comparison

		over temperature.
E8h	Configuration Override Byte	Location of the bits is defined in Table 4
E9h	Reserved	Reserved
EAh – EBh	Internal State Bytes	Location of the bits is defined in Table 4
ECh	I/O States 1	Location of the bits is defined in Table 4
EDh – EEh	D/A Out	Magnitude of the temperature compensated D/A outputs
EFh	Temperature Index	Address pointer to the look-up Arrays
F0h – FFh	Reserved	Reserved

Memory Location (Array 4)	Name of Location	Function of Location
00h – Ffh		D/A Current vs. Temp #1 (User-Defined Look-up Array #1)

Memory Location (Array 5)	Name of Location	Function of Location
00h – Ffh		D/A Current vs. Temp #2 (User-Defined Look-up Array #2)

TABLE 2

DETAIL MEMORY DESCRIPTIONS - A/D VALUES AND STATUS BITS

Byte	Bit	Name	Description
Converted analog values. Calibrated 16 bit data. (See Notes 1-2)			
96 (60h)	All	Temperature MSB	Signed 2's complement integer temperature (-40 to +125C) Based on internal temperature measurement
97	All	Temperature LSB	Fractional part of temperature (count/256)
98	All	V _{cc} MSB	Internally measured supply voltage in transceiver. Actual voltage is full 16 bit value * 100 uVolt.
99	All	V _{cc} LSB	(Yields range of 0 – 6.55V)
100	All	TX Bias MSB	Measured TX Bias Current in mA Bias current is full 16 bit value *(1/256) mA.
101	All	TX Bias LSB	(Full range of 0 – 256 mA possible with 4 uA resolution)
102	All	TX Power MSB	Measured TX output power in mW. Output is full 16 bit value *(1/2048) mW. (see note 5)
103	All	TX Power LSB	(Full range of 0 – 32 mW possible with 0.5 μ W resolution, or –33 to +15 dBm)
104	All	RX Power MSB	Measured RX input power in mW RX power is full 16 bit value *(1/16384) mW.

			(see note 6)
105	All	RX Power LSB	(Full range of 0 – 4 mW possible with 0.06 μ W resolution, or –42 to +6 dBm)
106	All	Reserved MSB	Reserved for 1 st future definition of digitized analog input
107	All	Reserved LSB	Reserved for 1 st future definition of digitized analog input
108	All	Reserved MSB	Reserved for 2 nd future definition of digitized analog input
109	All	Reserved LSB	Reserved for 2 nd future definition of digitized analog input
110	7	TX Disable	Digital state of the TX Disable Input Pin
110	6	Reserved	
110	5	Reserved	
110	4	Rate Select	Digital state of the SFP Rate Select Input Pin
110	3	Reserved	
110	2	TX Fault	Digital state of the TX Fault Output Pin
110	1	LOS	Digital state of the LOS Output Pin
110	0	Power-On-Logic	Indicates transceiver has achieved power up and data valid
111	7	Temp A/D Valid	Indicates A/D value in Bytes 96/97 is valid
111	6	V _{cc} A/D Valid	Indicates A/D value in Bytes 98/99 is valid
111	5	TX Bias A/D Valid	Indicates A/D value in Bytes 100/101 is valid
111	4	TX Power A/D Valid	Indicates A/D value in Bytes 102/103 is valid
111	3	RX Power A/D Valid	Indicates A/D value in Bytes 104/105 is valid
111	2	Reserved	Indicates A/D value in Bytes 106/107 is valid
111	1	Reserved	Indicates A/D value in Bytes 108/109 is valid
111	0	Reserved	Reserved

TABLE 3

DETAIL MEMORY DESCRIPTIONS – ALARM AND WARNING FLAG BITS

Alarm and Warning Flag Bits			
Byte	Bit	Name	Description
112	7	Temp High Alarm	Set when internal temperature exceeds high alarm level.
112	6	Temp Low Alarm	Set when internal temperature is below low alarm level.
112	5	V _{cc} High Alarm	Set when internal supply voltage exceeds high alarm level.
112	4	V _{cc} Low Alarm	Set when internal supply voltage is below

			low alarm level.
112	3	TX Bias High Alarm	Set when TX Bias current exceeds high alarm level.
112	2	TX Bias Low Alarm	Set when TX Bias current is below low alarm level.
112	1	TX Power High Alarm	Set when TX output power exceeds high alarm level.
112	0	TX Power Low Alarm	Set when TX output power is below low alarm level.
113	7	RX Power High Alarm	Set when Received Power exceeds high alarm level.
113	6	RX Power Low Alarm	Set when Received Power is below low alarm level.
113	5-0	Reserved Alarm	
114	All	Reserved	
115	All	Reserved	
116	7	Temp High Warning	Set when internal temperature exceeds high warning level.
116	6	Temp Low Warning	Set when internal temperature is below low warning level.
116	5	V _{cc} High Warning	Set when internal supply voltage exceeds high warning level.
116	4	V _{cc} Low Warning	Set when internal supply voltage is below low warning level.
116	3	TX Bias High Warning	Set when TX Bias current exceeds high warning level.
116	2	TX Bias Low Warning	Set when TX Bias current is below low warning level.
116	1	TX Power High Warning	Set when TX output power exceeds high warning level.
116	0	TX Power Low Warning	Set when TX output power is below low warning level.
117	7	RX Power High Warning	Set when Received Power exceeds high warning level.
117	6	RX Power Low Warning	Set when Received Power is below low warning level.
117	5	Reserved Warning	
117	4	Reserved Warning	
117	3	Reserved Warning	
117	2	Reserved Warning	
117	1	Reserved Warning	
117	0	Reserved Warning	
118	All	Reserved	
119	All	Reserved	

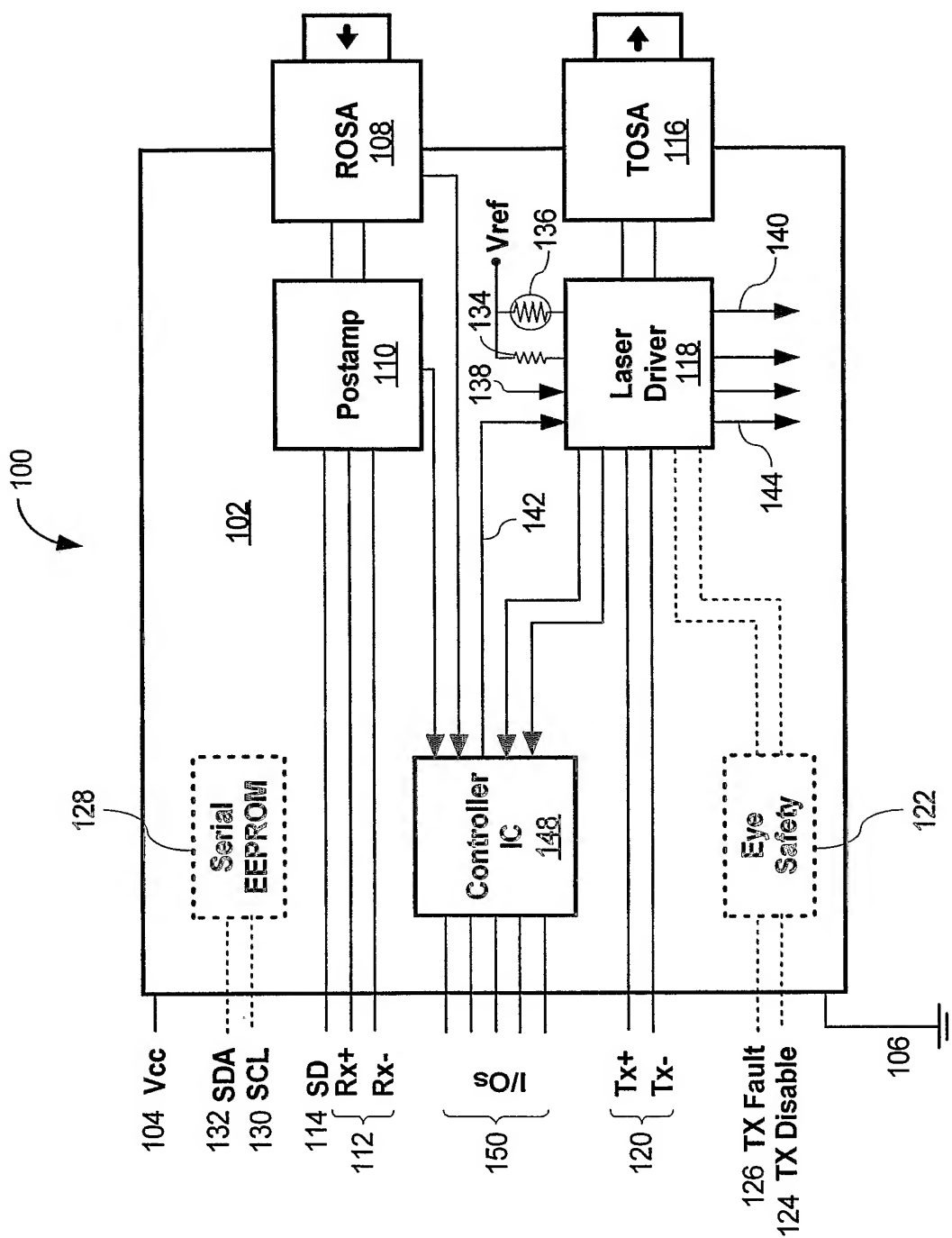
TABLE 4

Byte Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
X-out cntl0	T alrm hi set	T alrm lo set	V alrm hi set	V alrm lo set	B alrm hi set	B alrm lo set	P alrm hi set	P alrm lo set
X-out cntl1	R alrm hi set	R alrm lo set	B ft hi set	P ft hi set	R ft hi set	D-in inv set	D-in set	F-in inv set
X-out cntl2	F-in set	L-in inv set	L-in set	Aux inv set	Aux set	T alrm hi hib	T alrm lo hib	V alrm hi hib
X-out cntl3	V alrm lo hib	B alrm hi hib	B alrm lo hib	P alrm hi hib	P alrm lo hib	R alrm hi hib	R alrm lo hib	B ft hi hib
X-out cntl4	P ft hi hib	R ft hi hib	D-in inv hib	D-in hib	F-in inv hib	F-in hib	L-in inv hib	L-in hib
X-out cntl5	Aux inv hib	Aux hib	T alrm hi clr	T alrm lo clr	V alrm hi clr	V alrm lo clr	B alrm hi clr	B alrm lo clr
X-out cntl6	P alrm hi clr	P alrm lo clr	R alrm hi clr	R alrm lo clr	B ft hi clr	P ft hi clr	R ft hi clr	D-in inv clr
X-out cntl7	D-in clr	F-in inv clr	F-in clr	L-in inv clr	L-in clr	Aux inv clr	Aux clr	EE
X-out cntl8	latch select	invert	o-ride data	o-ride select	S reset data	HI enable	LO enable	Pullup enable
Prescale	<i>reserved</i>	<i>reserved</i>	<i>Reserved</i>	<i>reserved</i>	B^3	B^2	B^1	B^0
X-out delay	B^7	B^6	B^5	B^4	B^3	B^2	B^1	B^0
chip address	b^7	b^6	b^5	b^4	b^3	b^2	b^1	X
X-ad scale MSB	2^{15}	2^{14}	2^{13}	2^{12}	2^{11}	2^{10}	2^9	2^8
X-ad scale LSB	2^7	2^6	2^5	2^4	2^3	2^2	2^1	2^0
D/A cntl	source/sink	D/A #2 range			source/sink	D/A #1 range		
	1/0	2^2	2^1	2^0	1/0	2^2	2^1	2^0
config/O-ride	manual D/A	manual index	manual AD alarm	EE Bar	SW-POR	A/D Enable	Manual fast alarm	<i>reserved</i>
Internal State 1	D-set	D-inhibit	D-delay	D-clear	F-set	F-inhibit	F-delay	F-clear
Internal State 0	L-set	L-inhibit	L-delay	L-clear	<i>reserved</i>	<i>reserved</i>	<i>reserved</i>	<i>reserved</i>
I/O States 1	<i>reserved</i>	F-in	L-in	<i>reserved</i>	D-out	<i>reserved</i>	<i>reserved</i>	<i>reserved</i>
Margin #1	Reserved	Neg_Scale2	Neg_Scale1	Neg_Scale0	Reserved	Pos_Scale 2	Pos_Scale 1	Pos_Scale 0
Margin #2	Reserved	Neg_Scale2	Neg_Scale1	Neg_Scale0	Reserved	Pos_Scale 2	Pos_Scale 1	Pos_Scale 0

WHAT IS CLAIMED IS:

1. An optical transceiver module, comprising:
a housing;
a plurality of components disposed at least partially within said
5 housing, said components including:
an optical transmitter; an optical receiver; and
a power controller integrated circuit (IC) electrically coupled to at least
one of said plurality of components, where said power controller IC is
configured to perform power supply functions for said optical transceiver
10 module and said power controller IC includes multiple voltage regulators
providing power to said components at two or more voltages.
2. The optical transceiver module of claim 1, wherein at least one of said
multiple voltage regulators is a low drop-out voltage regulator configured to
receive an unregulated input voltage and configured to supply a regulated
15 output voltage to at least one of said components.
3. The optical transceiver module of claim 1, wherein at least one of said
multiple voltage regulators is a boost or buck regulator electrically coupled to
at least one of said components.
4. The optical transceiver module of claim 1, wherein said power
20 controller IC further includes a serial bus within said power controller IC.
5. The optical transceiver module of claim 4, wherein said multiple
voltage regulators are electrically coupled to said serial bus.
6. The optical transceiver module of claim 5, wherein said power
controller
25 IC further comprises a serial interface electrically coupled to said serial bus.
7. The optical transceiver module of claim 6, wherein said components
further comprise a main controller electrically coupled to said serial interface,
such that in use said main controller can control at least one of said multiple
voltage regulators.
- 30 8. The optical transceiver module of claim 5, wherein said voltage
regulators are individually addressable.

9. The optical transceiver module of claim 1, wherein at least one of said voltage regulators includes an Avalanche Photo Diode (APD) voltage supply.
10. The optical transceiver module of claim 1, wherein at least one of said voltage regulators is adjustable.
- 5 11. The optical transceiver module of claim 1, wherein said power controller IC further includes a plurality of components selected from a group consisting of: an analog to digital converter, a temperature sensor, a digital to analog converter, a logic module, an inrush current limiter, and a processor management module.
- 10 12. The optical transceiver module of claim 1, wherein said components further include a laser driver IC electrically coupled to said optical transmitter, and a post-amplifier IC electrically coupled to said optical receiver.
13. The optical transceiver module of claim 1, wherein said components further include a main controller IC electrically coupled to at least one of said components.
- 15 14. The optical transceiver module of claim 13, wherein said power controller IC is electrically coupled to and controlled by said main controller IC.



(PRIOR ART)
FIG. 1

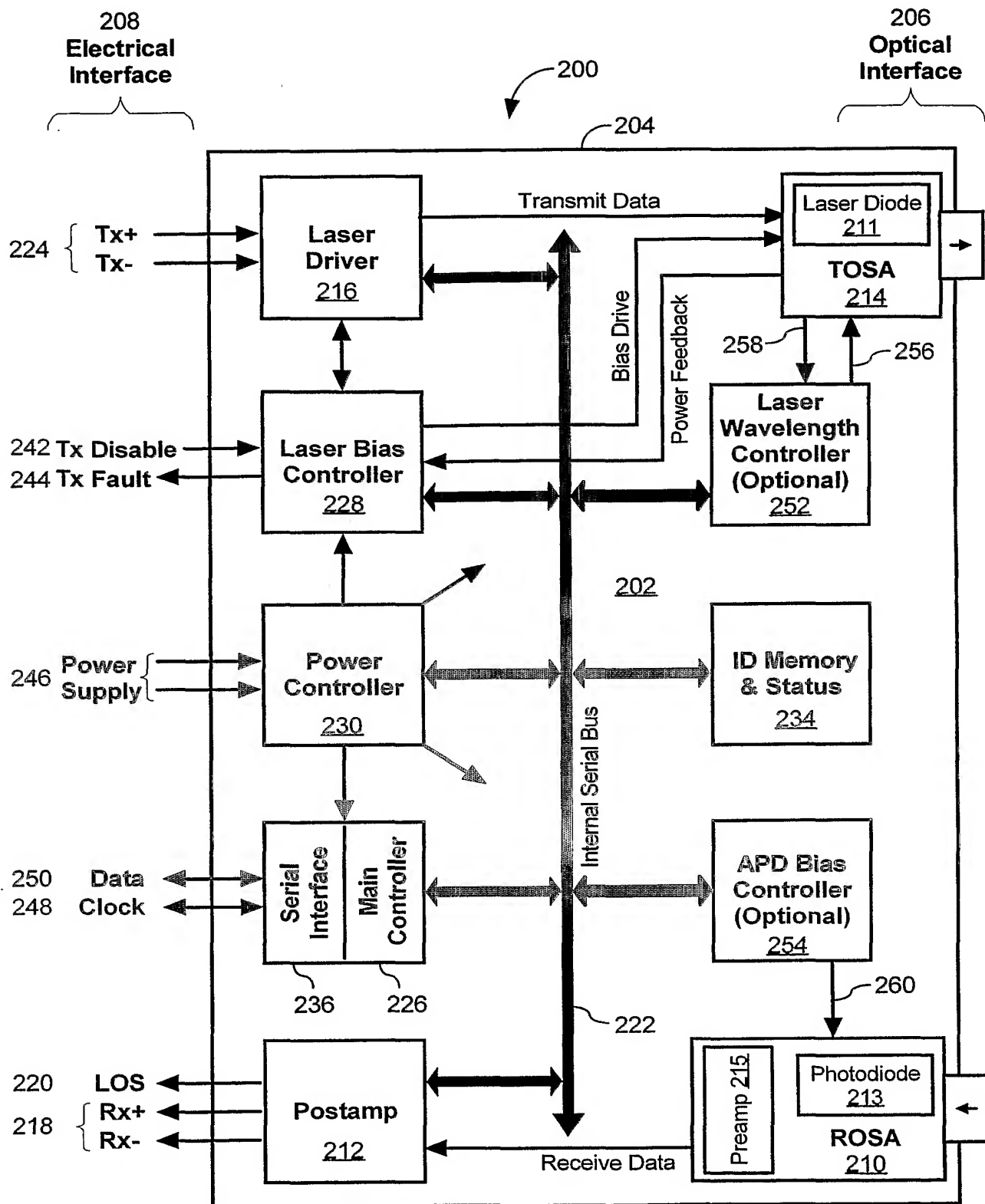


FIG. 2A

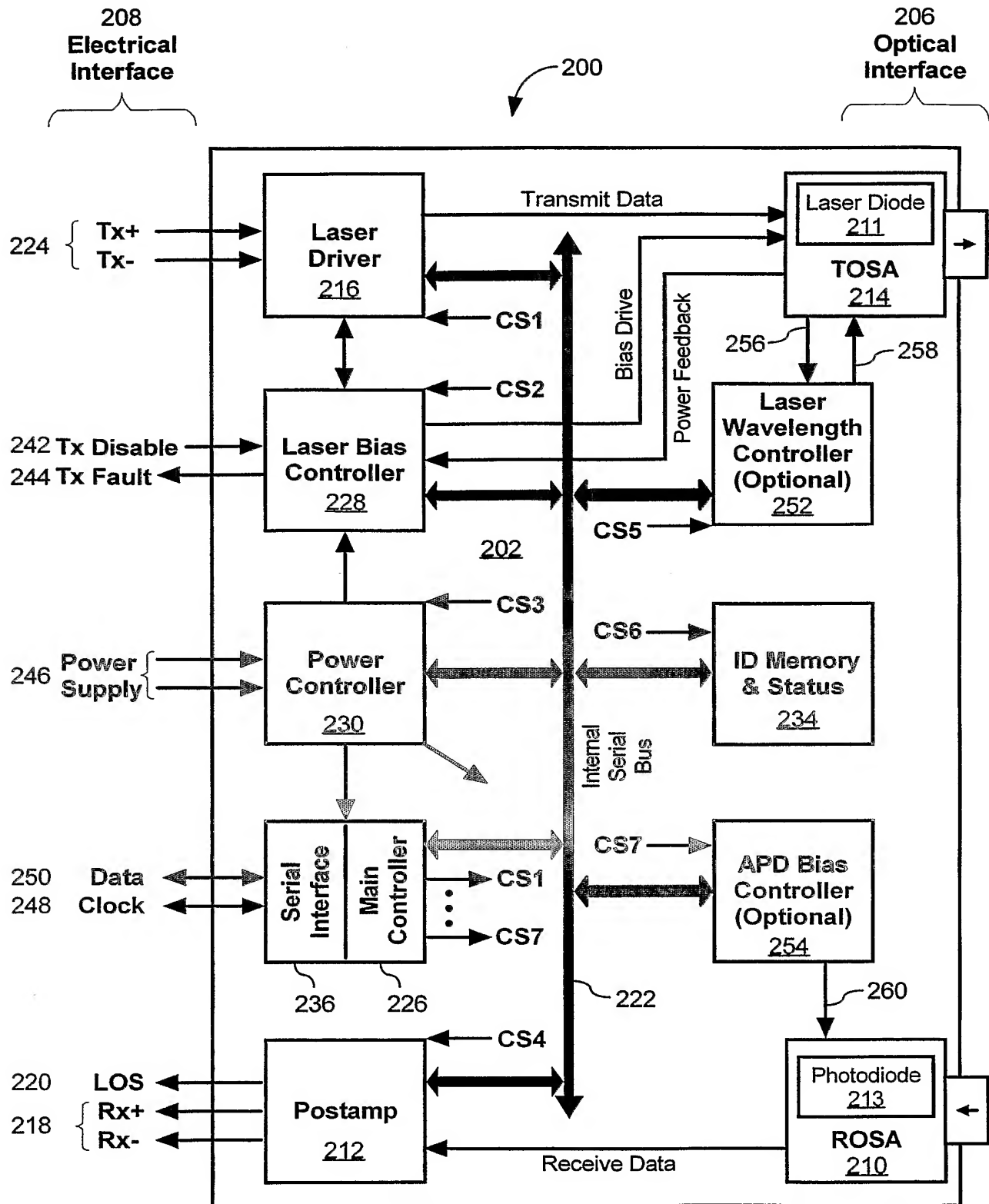


FIG. 2B

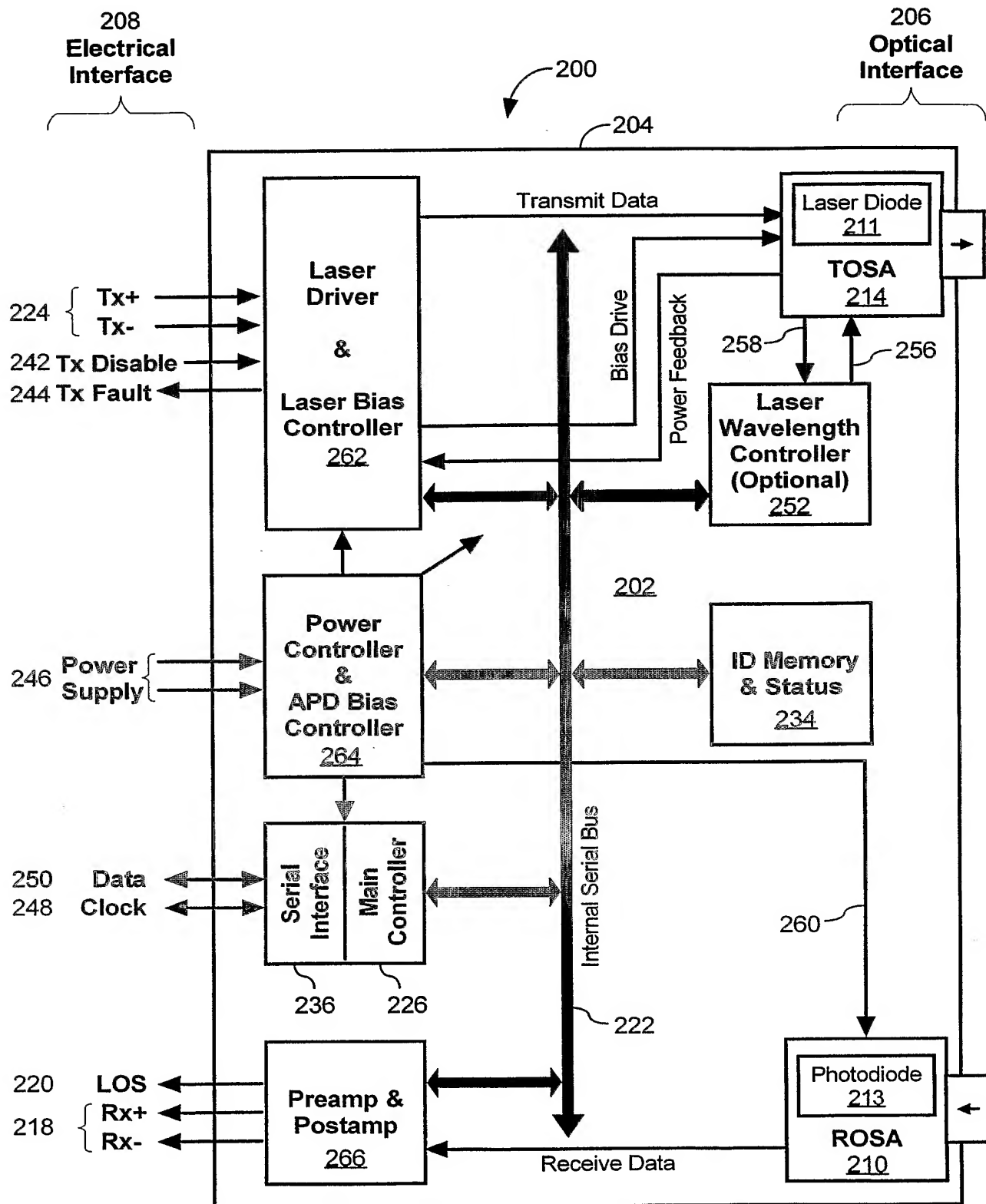


FIG. 2C

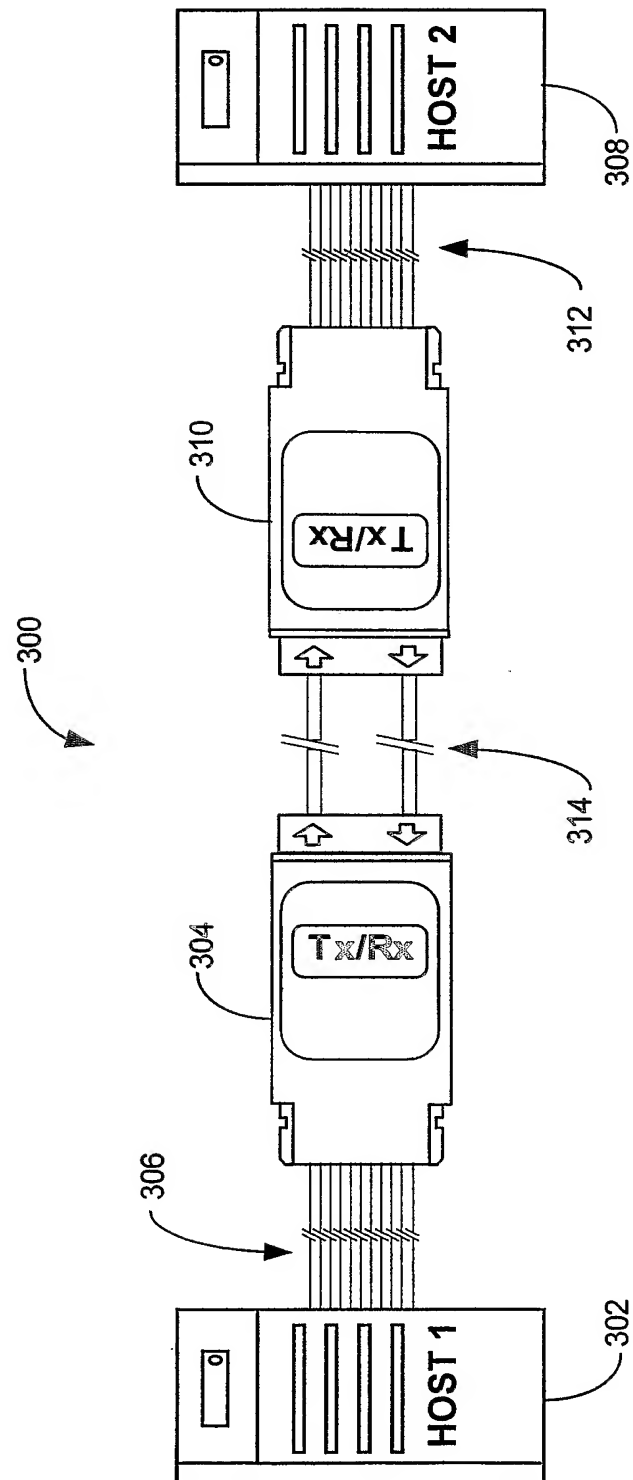


FIG. 3

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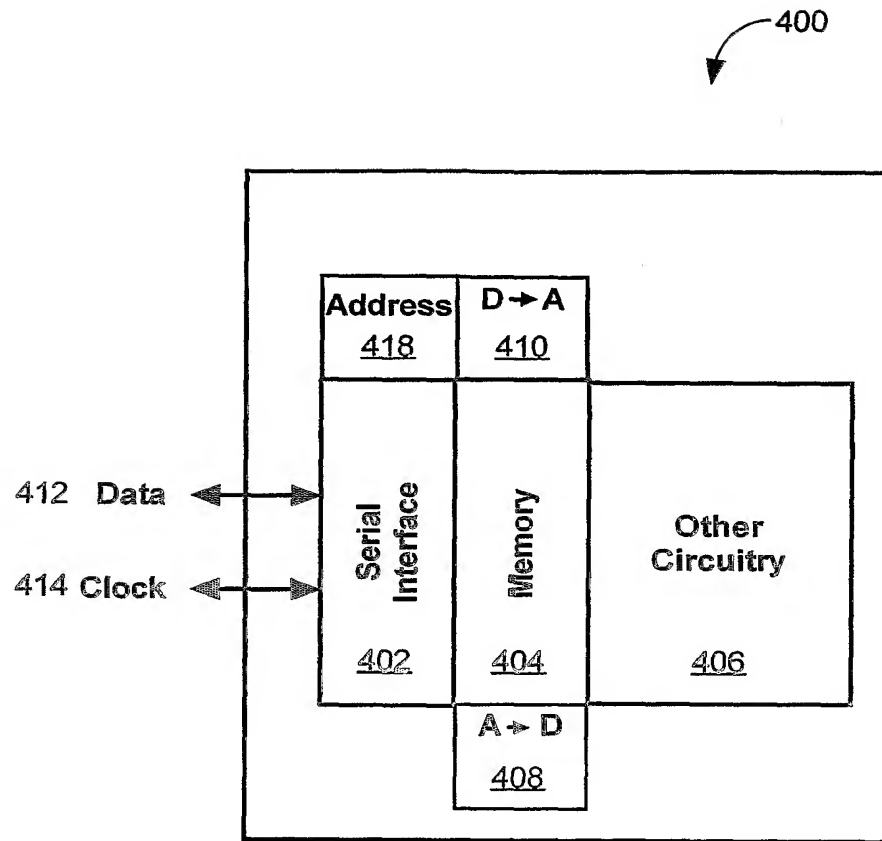


FIG. 4A

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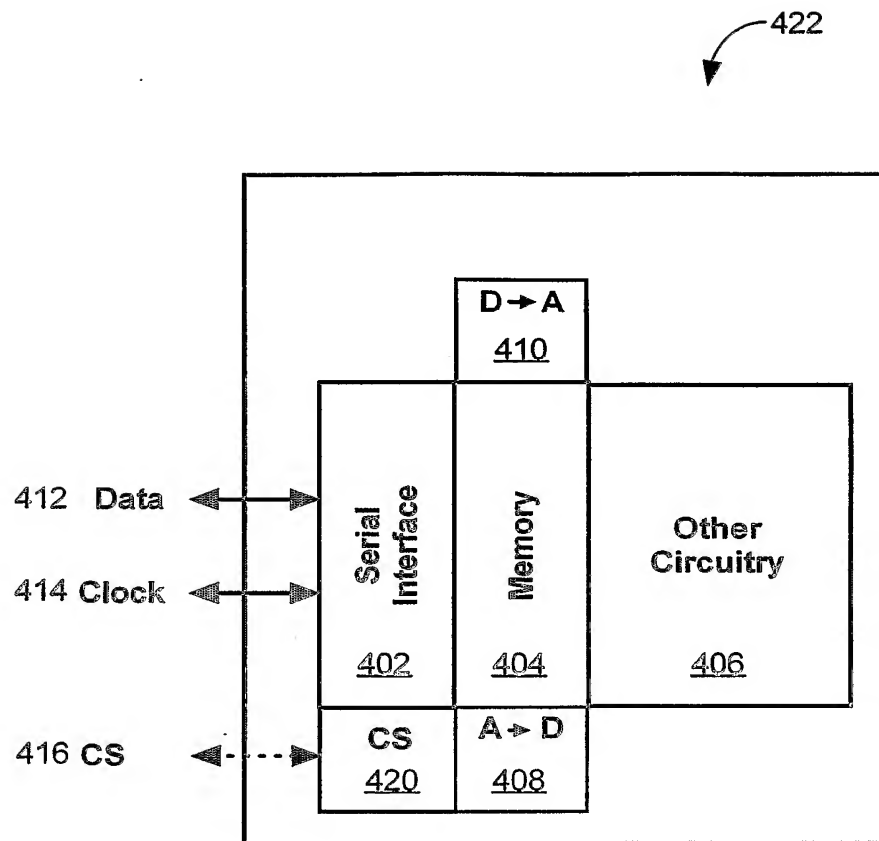


FIG. 4B

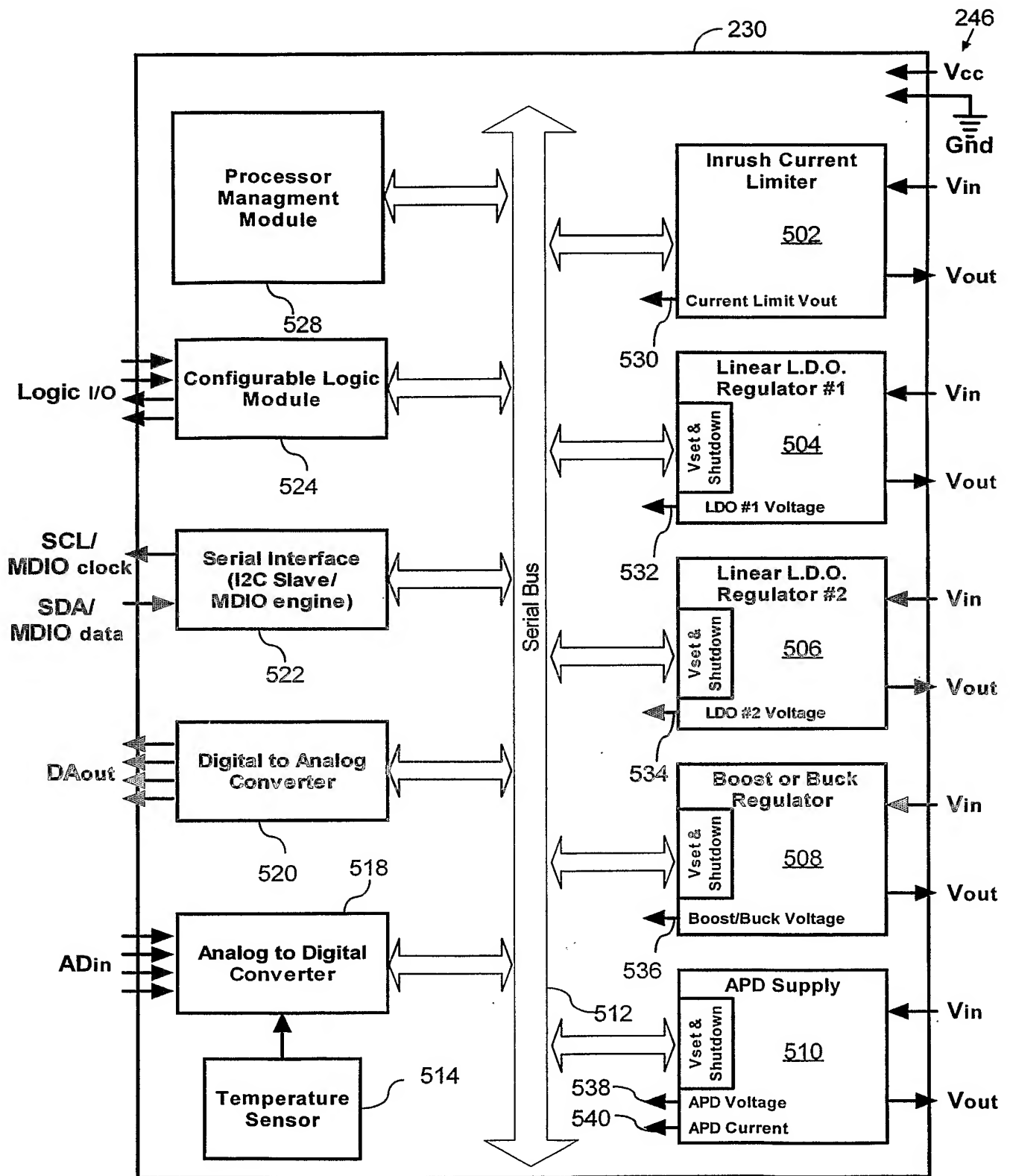


FIG. 5